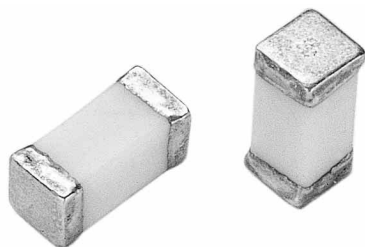


SMT Time-Lag Fuse

Subminiature Surface Mount Fuses

6125T



Catalog Symbol: 6125T

Time-Lag

Voltage Rating: 125V AC/DC

Interrupting Rating:

50 Amp AC, Power Factor = 1.0

50 Amp DC, Battery Source

Physical Size:

EIA SOCM-6125AA.

6.1 × 2.5 × 2.5 mm (L × W × H)

Agency Approvals:

Universal Modular Fuse, IEC127-4

UL Recognition, Std. 248-14, File E19180, Guide JDYX2

CSA Certified, C22.2 No. 248.14, File 53787, Class 1422-30

Additional Approvals Pending

General Information:

- Surge resistant time-lag fuse.
- Brazed seals: body to end plates.
- Compatible with wave soldering.
- Excellent environmental integrity.
- Economical overcurrent protection.

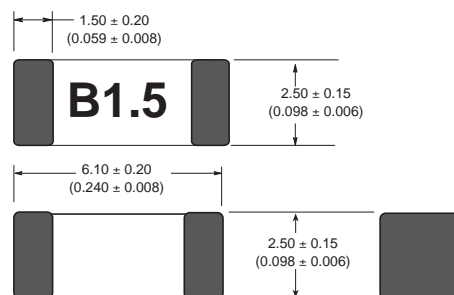
Time Current Characteristics:

125% of Rating: carry 1 hour min.

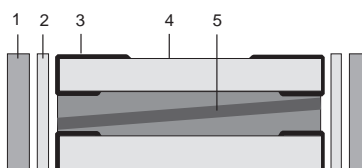
200%: Open within 2 minutes.

1000%: Open within 0.01 to 0.1 seconds.

Dimensions - mm (inches)



Construction



1. Brass end plate (one of two)*.
2. High temperature brazing alloy preform (one of two).
3. Silver metallization*.
4. Ceramic body.
5. Spiral wound fusible element.

*End terminations plated with Ni and 90/10 Sn/Pb after assembly.

Packaging and Ordering Information:

Tape and Reel: Standard 12mm tape, in compliance with EIA-RS481 (equivalent to IEC 286, Part 3).

6125T	(See Table)
Product Symbol	Rated Current

Package Code

TR = 1,000 pieces on tape on a 178mm reel.

SP = 50 pieces on tape in a plastic box.

Contact Bussmann if other package quantities are required.

CE CE logo denotes compliance with European Union Low Voltage Directive (50-1000 VAC, 75-1500 VDC). Refer to BIF document #8002 or contact Bussmann Application Engineering at 314-527-1270 for more information.

Electrical Characteristics

Part Number (xx=Package Code)	Current Rating (Amperes)	Marking	Typ. Resistance @ ≤ 10% Rated Current (Ohms)	Max. Power Dissipation @ 125% of Rated Current (Milliwatts)
XX/6125T-250mA	.25	B.25	4.5	500
XX/6125T-500mA	.5	B0.5	1.0	500
XX/6125T-1A	1	B1A	0.25	500
XX/6125T-1.5A	1.5	B1.5	0.10	500
XX/6125T-2A	2	B2A	0.06	500
XX/6125T-3A	3	B3A	0.04	1000
XX/6125T-4A	4	B4A	0.03	1200
XX/6125T-5A	5	B5A	0.02	1200

General Notes:

1. Device designed to carry 125% of rated current for one hour minimum. An operating current of 80% or less of rated current is recommended, with further derating required at elevated ambient temperatures.
2. All measurements made at 23 ± 3°C ambient temperature with the device mounted on a suitable circuit board trace.

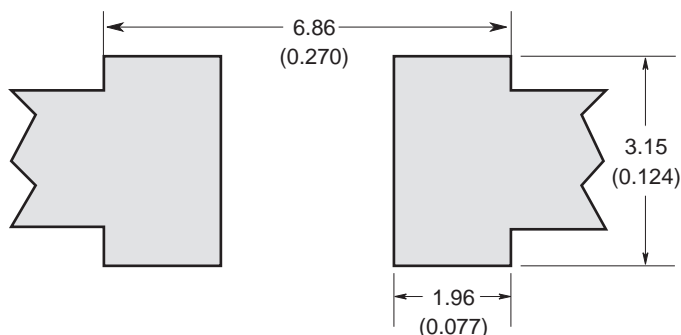
SMT Time-Lag Fuse

Subminiature Surface Mount Fuses

6125T



Recommended Land Pattern - mm (inches)

**Environmental Specifications:****Operating Temperature Range:**

-65 to +125°C, with proper derating.

Thermal Shock:

MIL-STD-202, Method 107, Test Condition B (-65 to 125°C), 1000 cycles, fuses soldered to FR-4 glass-epoxy circuit board.

Vibration:

MIL-STD-202, Method 204, Test Condition C (55 to 2000 HZ, 10G).

Solderability:

Withstands 60 seconds above 200°C, 260°C maximum.

Moisture Resistance:

MIL-STD-202, Method 106, 10 day cycle.

Solder Leach Resistance & Terminal Adhesion:

EIA - 576 (30 seconds submersion in 260°C tin-lead solder).

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